PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hideki OGAWA	04/19/2011
Atsushi TANADA	04/19/2011
Hitoshi MATSUURA	04/20/2011
Kiyoshi TANAKA	04/20/2011
Hiroshi KISHI	04/21/2011
Kenji KAWANO	04/21/2011

RECEIVING PARTY DATA

Name:	TAIYO YUDEN CO.,LTD.
Street Address:	16-20, Ueno 6-chome
City:	Taito-ku, Tokyo
State/Country:	JAPAN
Postal Code:	110-0005

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13092381

CH $40.00 13092381

CORRESPONDENCE DATA

Fax Number: (949)457-8297

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 949-457-8296
Email: KAPAT@KAPATLAW.COM
Correspondent Name: Law Office of Katsuhiro Arai
Address Line 1: 22471 Aspan Street
Address Line 2: Suite 205 C
Address Line 4: Lake Forest, CALIFORNIA 92630

ATTORNEY DOCKET NUMBER:	TAYUX.090287US

NAME OF SUBMITTER:	Katsuhiro Arai

Total Attachments: 3
source=ASSIGNMENT_tayux-090287us_20110422#page1.tif
source=ASSIGNMENT_tayux-090287us_20110422#page2.tif
source=ASSIGNMENT_tayux-090287us_20110422#page3.tif

ASSIGNMENT

WHEREAS, the undersigned inventor(s) have/has invented certain new and useful improvements in a

COIL-TYPE ELECTRONIC COMPONENT AND ITS MANUFACTURING METHOD

for which the undersigned inventor(s)

☒ will file an application for Letters Patent in the United States identified also as Attorney Docket No. TAYUX.090287US (hereinafter "Application");

☐ have/has filed an application, International Application No. PCT/JP ___ / ______, filed _______, under the Patent Cooperation Treaty, which will enter the U.S. National Phase under 35 U.S.C. §371 (hereinafter "Application");

☐ have/has filed an application for Letters Patent in the United States, Application No. ________, filed ______ (hereinafter "Application");

AND WHEREAS, TAIYO YUDEN CO., LTD., a Japanese corporation, with its principal place of business at 16-20 , Ueno 6-chome , Taito-ku ,Tokyo ,110-0005, Japan (hereinafter "ASSIGNEE"), desires to acquire the entire right, title, and interest in and to said improvements and said Application;

NOW, THEREFORE, in return for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor(s) do/does hereby acknowledge that the undersigned inventor(s) have/has sold, assigned, transferred and set over, and by these presents do/does hereby sell, assign, transfer and set over, unto said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under said improvements, and said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and the undersigned inventor(s) hereby authorize(s) and request(s) the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND THE UNDERSIGNED INVENTOR(S) DO/DOES HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance;

AND THE UNDERSIGNED INVENTOR(S) HEREBY covenant(s) and agree(s) that the undersigned inventor(s) will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to the undersigned inventor(s) respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, the undersigned inventor(s) execute(s) this assignment:

NAME OF SOLE OR FIRST INVENTOR	
first and middle [if any] Hideki	FAMILY NAME OGAWA
Inventor's Signature Hideki Ogawa	Date 4/19/2011
Witness Tsuyoshi Matsumoto	
NAME OF SECOND INVENTOR	
first and middle [if any] Atsushi	FAMILY NAME TANADA
Inventor's Signature Atsushi Tanada	Date 4/19/2011
Witness Hidenori Aoki	
NAME OF THIRD INVENTOR	
first and middle [if any] Hitoshi	FAMILY NAME MATSUURA
Inventor's Signature Hitoshi Matsuura	Date 4/20/2011
Witness Nobuyuki Koide	
NAME OF FOURTH INVENTOR	
first and middle [if any] Kiyoshi	FAMILY NAME TANAKA
Inventor's Signature Kiyoshi Tanaka	Date 4/20/2011
Witness Tetsuyuki Suzuki	

NAME OF FIFTH INVENTOR	
first and middle [if any] Hiroshi	FAMILY NAME KISHI
Inventor's Signature Hiroshi Kishi	Date 4/21/2011
Witness Keiichi Hatano.	
NAME OF SIXTH INVENTOR	
first and middle [if any] Kenji	FAMILY NAME KAWANO
Inventor's Signature	Date 4/21/2011
Witness	